

zQSFP+/QSFP28

TE Internal #: 2227666-3

zQSFP+, Cage Assembly with Integrated Connector, .8mm [.032in]

Centerline, Signal, Operating Temperature Range -55 – 105 °C [-67

- 221 °F]

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Connectors > Pluggable IO Connectors & Cages



Form Factor: **zQSFP+**

Pluggable I/O Product Type: Cage Assembly with Integrated Connector

Centerline (Pitch): .8 mm [.032 in]

Sealable: No

Circuit Application: Signal

Features

Product Type Features

Cage Type	Stacked
Form Factor	zQSFP+
Pluggable I/O Product Type	Cage Assembly with Integrated Connector
Sealable	No
Configuration Features	
Number of Positions	76
Number of Ports	2
Port Matrix Configuration	2 x 1
Electrical Characteristics	
Data Rate (Max)	28 Gb/s
Contact Features	
Contact Current Rating (Max)	.5 A

Tin

Gold

Gold (Au)

.76 μm[30 μin]

Termination Features

Contact Underplating Material

Contact Mating Area Plating Material

PCB Contact Termination Area Plating Material

Contact Mating Area Plating Material Thickness



Termination Method to PCB	Through Hole - Press-Fit
Termination Post & Tail Length	2 mm[.079 in]
Housing Features	
Cage Material	Nickel Silver
Centerline (Pitch)	.8 mm[.032 in]
Dimensions	
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Pluggable I/O Applications	SFP+ Stacked Belly-to-Belly
Heat Sink Compatible	No
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box & Tray
Other	
Included Lightpipe	Yes
EMI Containment Feature Type	Internal/External EMI Springs

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free



Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

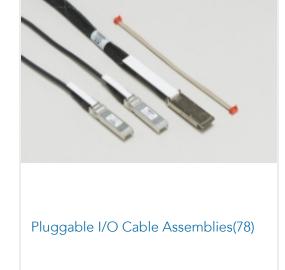
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

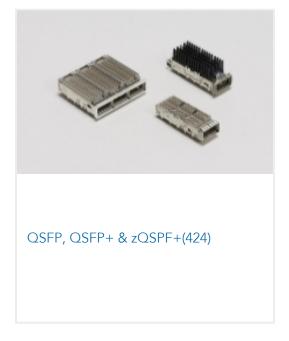




Also in the Series | zQSFP+/QSFP28







Customers Also Bought























Documents

Product Drawings

ZQSFP+ STACKED, 2X1, THRU BEZEL W SPRING

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2227666-3_3.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2227666-3_3.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2227666-3_3.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Datasheets & Catalog Pages

QSFP28/56 and zQSFP+ Interconnects

English

Product Specifications

Application Specification

English